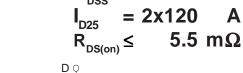
TrenchMV[™] Power MOSFETs Common-Gate Pair

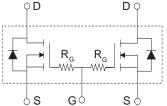
IXTL2x220N075T

Pair

(Electrically Isolated Back Surface)

N-Channel Enhancement Mode Avalanche Rated

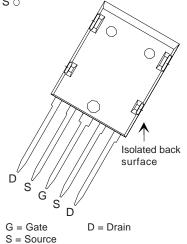




ISOPLUS i5-Pak™ (IXTL)

Symbol	Test Conditions	Maximum Ratings		
V _{DSS} V _{DGR}	$T_J = 25^{\circ}\text{C}$ to 175°C $T_J = 25^{\circ}\text{C}$ to 175°C; $R_{GS} = 1 \text{ M}\Omega$	75 75	V V	
V _{GSM}	Transient	± 20	V	
I _{D25}	$T_{\rm C} = 25^{\circ}$ C (Combined die total = 240 A)	120	А	
LRMS	Package Current Limit, RMS (Combined die total = 150 A)	75	Α	
I _{DM}	$T_{\rm C} = 25^{\circ}$ C, pulse width limited by $T_{\rm JM}$	600	Α	
I _{AR} E _{AS}	$T_{c} = 25^{\circ}C$ $T_{c} = 25^{\circ}C$	25 1.0	A J	
dv/dt	$I_{s} \leq I_{DM}, di/dt \leq 100 A/\mu s, V_{DD} \leq V_{DSS}$ $T_{J} \leq 175^{\circ}C, R_{g} = 3.3 \Omega$	3	V/ns	
P _D	T _c = 25°C	150	W	
T _J T _{JM} T _{stg}		-55 +175 175 -55 +175	°C °C °C	
T _L T _{SOLD}	1.6 mm (0.062 in.) from case for 10 s Plastic body for 10 seconds	300 260	°C	
V _{ISOL}	50/60 Hz, $t = 1$ minute, $I_{ISOL} < 1$ mA, RMS	2500	V	
F _c	Mounting force	20120/4.525	N/lb.	
Weight		9	g	

(T _J = 25°C ।	Test Conditions unless otherwise specified)		Cha Min.	aracteris Typ.	tic Valu Max.	es
BV _{DSS}	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		75			V
V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		2.0		4.0	V
I _{GSS}	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$				± 200	nA
I _{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0 V$	T _J = 150°C			5 250	μΑ μΑ
R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}, \text{ Note}$	es 1, 2			5.5 r	mΩ



- Ultra-low On Resistance
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
 - easy to drive and to protect
- 175 °C Operating Temperature

Advantages

Features

- Easy to mount
- Space savings
- High power density

Applications

- Automotive
 - Motor Drives
 - 42V Power Bus
 - ABS Systems
- DC/DC Converters and Off-line UPS
- Primary Switch for 24V and 48V Systems
- High Current Switching Applications

All ratings and parametric values are per each MOSFET die unless otherwise specified.

DS99750(01/07)

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Symbol	Test Conditions		Characteristic Values C unless otherwise specified)		
		Min.	Тур.	Max.	
g_{fs}	$V_{DS} = 10 \text{ V}; I_{D} = 60 \text{ A}, \text{ Note 1}$	75	120	S	
R_{g}			3	Ω	
C _{iss}			7700	pF	
C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		1100	pF	
C _{rss}			230	pF	
t _{d(on)}			29	ns	
t _r	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \text{ V}_{DSS}, I_{D} = 2$	5 A	65	ns	
$\mathbf{t}_{d(off)}$	$R_{_{\rm G}}$ = 3.3 Ω (External)		55	ns	
t,			47	ns	
$\mathbf{Q}_{g(on)}$			165	nC	
\mathbf{Q}_{gs}	$V_{GS} = 10 \text{ V}, V_{DS} = 0.5 \text{ V}_{DSS}, I_{D} = 28$	5 A	40	nC	
\mathbf{Q}_{gd}			50	nC	
R_{thJC}				1.0 °C/W	
R _{thCS}			0.5	°C/W	

Source-Drain Diode

Characteristic Values

T_J = 25°C unless otherwise specified)

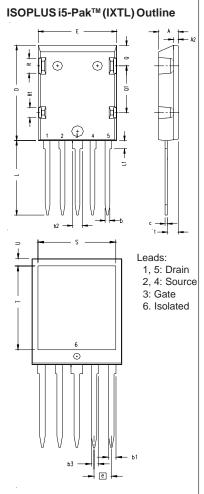
Symbol	Test Conditions	Min.	Typ.	ос зресп Мах.	
I _s	$V_{GS} = 0 V$			220	Α
I _{SM}	Pulse width limited by $T_{_{\rm JM}}$			600	Α
V _{SD}	$I_{\rm F} = 50 \text{ A}, V_{\rm GS} = 0 \text{ V}, \text{ Note 1}$			1.0	V
t _{rr}	$I_F = 25 \text{ A}, -di/dt = 100 \text{ A}/\mu\text{s}$		50		ns
	$V_R = 40 \text{ V}, V_{GS} = 0 \text{ V}$				

Notes: 1. Pulse test: $t \le 300 \mu s$, duty cycle d $\le 2 \%$;

2. Drain and Source Kelvin contacts must be located less than 5 mm from the plastic body.

ADVANCETECHNICALINFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.



out i	INCHES		MILLIMETERS		
SYM	MIN	MAX	MiN	MAX	
Α	.190	.205	4.83	5.21	
A1	.102	.118	2.59	3.00	
A2	.046	.055	1,17	1.40	
b	.045	.055	1,14	1.40	
ь1	.063	.072	1.60	1.83	
b2	.100	.110	2.54	2.79	
b3	.058	.068	1.47	1.73	
С	.020	.029	0.51	0.74	
D	1.020	1.040	25.91	26.42	
E	.770	.799	19.56	20.29	
е	.150 BSC		3.81	3.81 BSC	
L	.780	.820	19.81	20.83	
L1	.080	.102	2.03	2.59	
Q	.210	.235	5.33	5.97	
Q1	.490	.513	12.45	13.03	
R	.150	.180	3.81	4.57	
R1	.100	.130	2.54	3.30	
S	.668	.690	16.97	17.53	
T	.801	.821	20.34	20.85	
U	.065	.080	1.65	2.03	

Note:

- 1. TAB 6 Electrically isolated from the other pins.
- 2. All leads and tab are tin plated.

IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by 4,835,592 5,049,961 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 6,710,405B2 6,710,463 one or moreof the following U.S. patents: 4,850,072 4,881,106 5,017,508 5,034,796 5,063,307 5,187,117 5,381,025 5,486,715 6,259,123 B1 6,534,343 6,583,505 6,759,692 7,063,975 B2 6771478 B2 7,071,537 6,306,728 B1